# Nch 30V 39A Power MOSFET

$V_{\mathrm{DSS}}$	30V
R <sub>DS(on)</sub> (Max.)	5.3mΩ
I <sub>D</sub>	±39A
$P_D$	17W

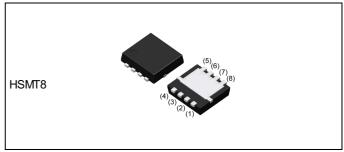
# Features

- 1) Low on resistance
- 2) High Power Package (HSMT8)
- 3) Pb-free lead plating; RoHS compliant
- 4) Halogen Free
- 5) 100% Rg and UIS tested

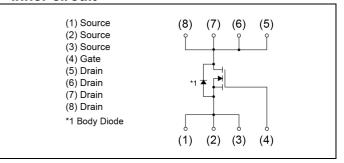
# Application

Switching

## Outline



## ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	3000
	Taping code	ТВ
	Marking	E150BN

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V <sub>DSS</sub>	30	V
Continuous dusin suument	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±39	Α
Continuous drain current	T <sub>a</sub> = 25°C	I <sub>D</sub>	±15	Α
Pulsed drain current	l <sub>DP</sub> *2	±60	Α	
Gate - Source voltage	$V_{GSS}$	±20	V	
Avalanche current, single pulse		I <sub>AS</sub> *3	15	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	16	mJ	
		P <sub>D</sub> *1	17	W
Power dissipation		P <sub>D</sub> *4	2.0	W
Junction temperature	T <sub>j</sub>	150	°C	
Operating junction and storage temp	T <sub>stg</sub>	-55 to +150	°C	

## ●Thermal resistance

Doromotor	Curah al	Values			l limit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	7.3	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	62.5	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymahal	Symbol Conditions		Values		
Parameter	Symbol			Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	30	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = 1 \text{mA}$ referenced to 25°C		-	21	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	-	1	1	μА
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 16V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3	-	mV/°C
Static drain - source	D *3	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A	-	3.8	5.3	0
on - state resistance	R <sub>DS(on)</sub> *3	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 15A	-	5.3	7.4	mΩ
Gate resistance	$R_{G}$	f=1MHz, open drain	-	2.3	-	Ω
Forward Transfer Admittance	Y <sub>fs</sub>  *3	V <sub>DS</sub> = 5V, I <sub>D</sub> = 15A	18	-	-	S

<sup>\*1</sup>  $T_c$ =25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $\simeq$  0.1mH, V<sub>DD</sub> = 15V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a Cu board (40×40×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions		Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	UIIIL	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	3000	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15V	-	360	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	260	-		
Turn - on delay time	t <sub>d(on)</sub> *3	$V_{DD} \simeq 15V, V_{GS} = 10V$	-	11	-		
Rise time	<b>t</b> <sub>r</sub> *3	I <sub>D</sub> = 7.5A	1	42	1	no	
Turn - off delay time	t <sub>d(off)</sub> *3	$R_L \simeq 2.0\Omega$		55	-	ns	
Fall time	t <sub>f</sub> *3	$R_G = 10\Omega$	-	10	-		

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymah al	Conditions		Values			l limit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate above	O *3		V <sub>GS</sub> = 10V	-	45	-	
Total gate charge	Q <sub>g</sub> *3	V <sub>DD</sub> ≃ 15V		-	23	-	~C
Gate - Source charge	Q <sub>gs</sub> *3	I <sub>D</sub> = 15A	V <sub>GS</sub> = 4.5V	-	5.5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *3			-	7.0	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions		Values			Unit	
raiametei	Symbol	Conditions		Тур.	Max.	Offic	
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	1.67	Α	
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	60	Α	
Forward voltage	V <sub>SD</sub> *3	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

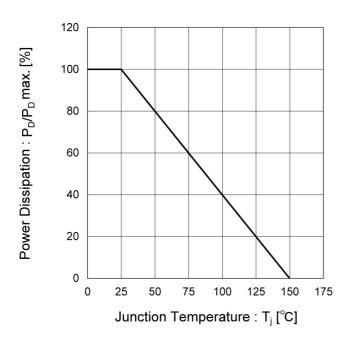
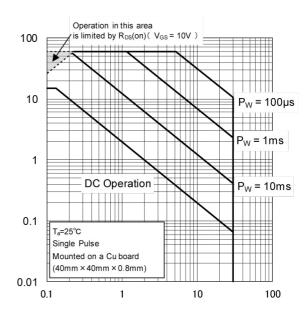


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

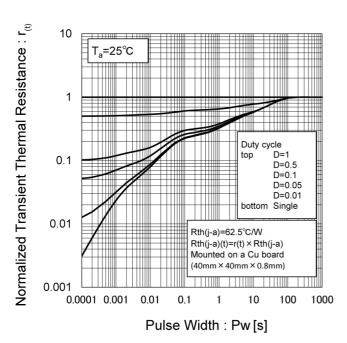
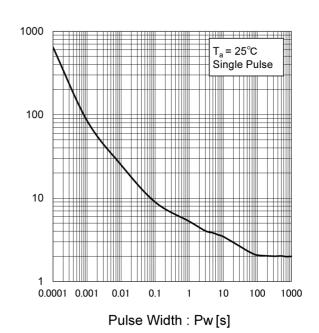


Fig.4 Single Pulse Maximum Power dissipation



Peak Transient Power : P(W)

Fig.5 Typical Output Characteristics(I)

15 14 V<sub>GS</sub>= 10V V<sub>GS</sub>= 3V 13 V<sub>GS</sub>= 4.5V V<sub>GS</sub>= 4V\_ 12 V<sub>GS</sub>= 2.8V Drain Current : I<sub>D</sub> [A] 11 10 9 8 7 6 5 V<sub>GS</sub>= 2.5V 4 3 2 T<sub>a</sub>=25°C Pulsed 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.6 Typical Output Characteristics(II)

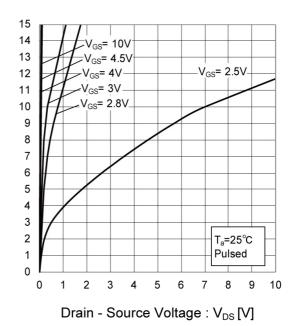


Fig.7 Breakdown Voltage vs.
Junction Temperature

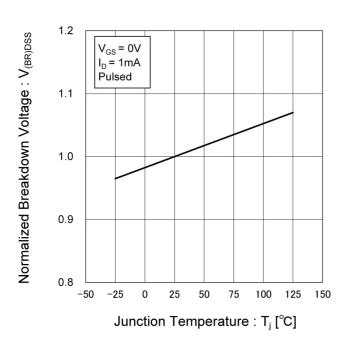
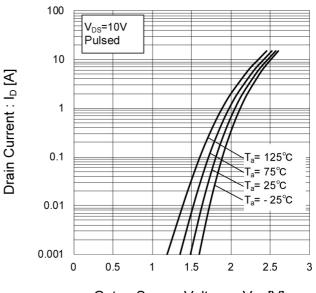


Fig.8 Typical Transfer Characteristics



Gate - Source Voltage :  $V_{GS}[V]$ 

Drain Current : I<sub>D</sub> [A]

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

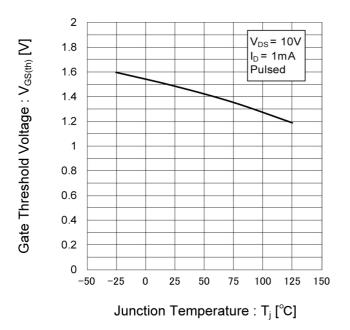


Fig.10 Forward Transfer Admittance vs.
Drain Current

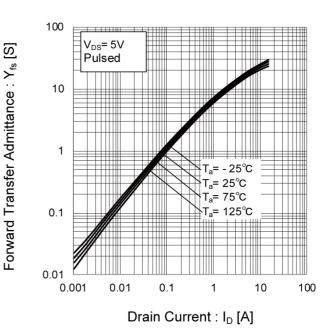


Fig.11 Drain Current Derating Curve

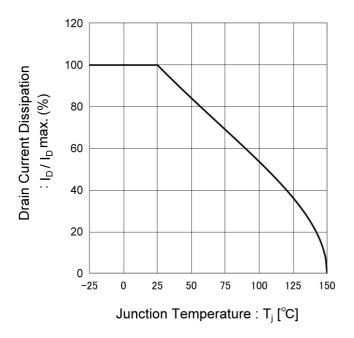


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

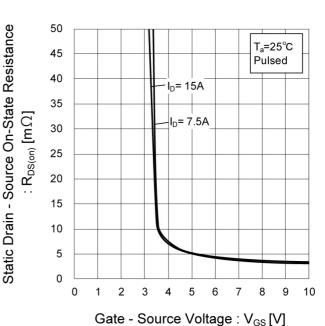


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

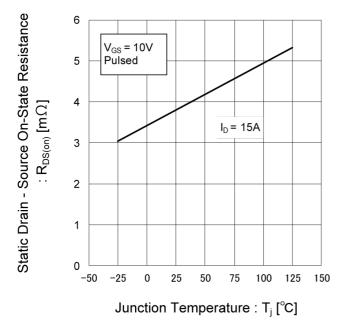


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

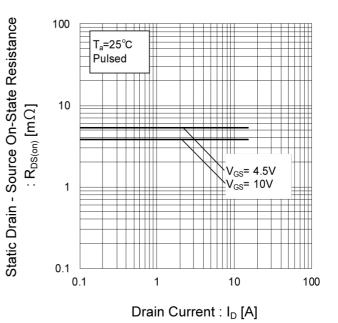


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

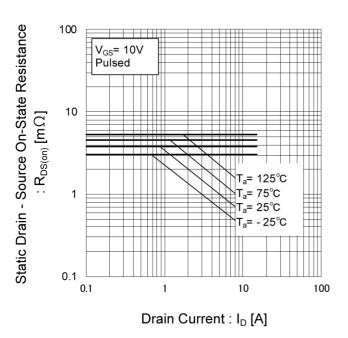


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

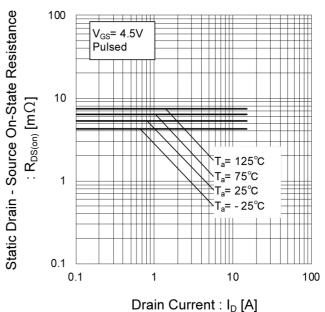


Fig.17 Typical Capacitance vs.

Drain - Source Voltage

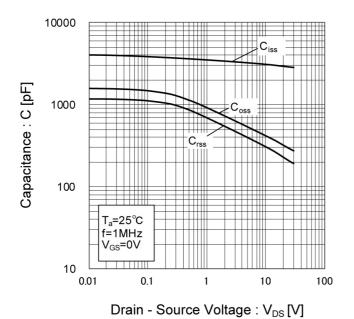


Fig.18 Switching Characteristics

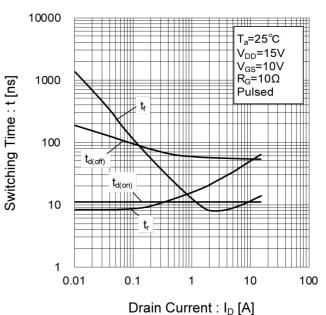


Fig.19 Dynamic Input Characteristics

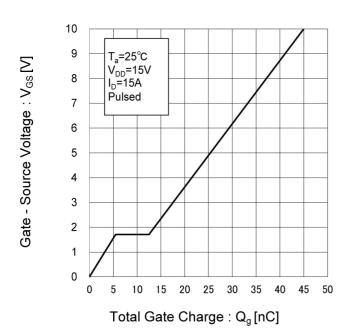
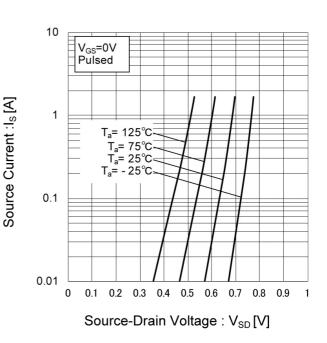


Fig.20 Source Current vs.

Source Drain Voltage



## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

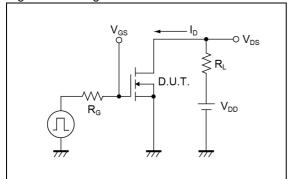


Fig.1-2 Switching Waveforms

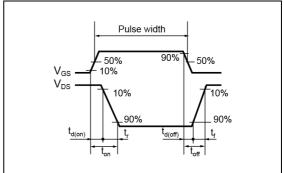


Fig.2-1 Gate Charge Measurement Circuit

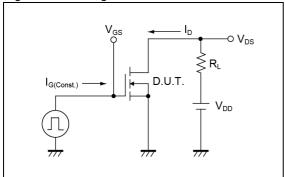


Fig.2-2 Gate Charge Waveform

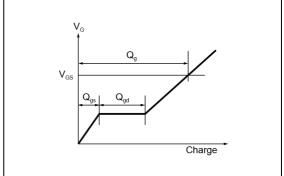


Fig.3-1 Avalanche Measurement Circuit

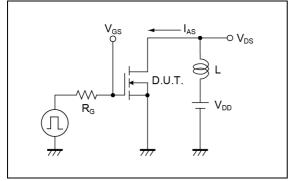
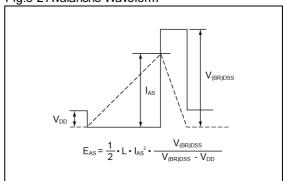


Fig.3-2 Avalanche Waveform



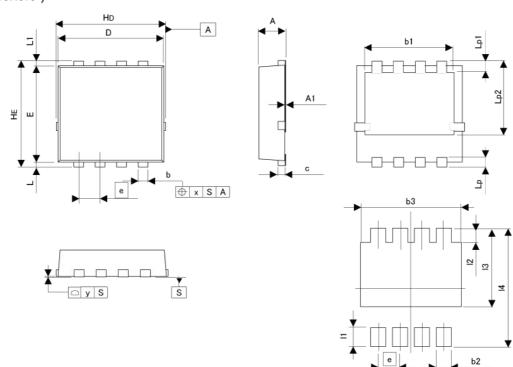
### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

## Dimensions

## HSMT8

(3.3x3.3)



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INC	HES	
DIIVI	MIN	MAX	MIN	MAX	
Α	0.70	0.90	0.028	0.035	
A1	0.00	0.05	0.000	0.002	
b	0.27	0.37	0.011	0.015	
b1	2.50	2.70	0.098	0.106	
С	0.10	0.30	0.004	0.012	
D	3.10	3.30	0.122	0.130	
E	2.90	3.10	0.114	0.122	
е	0.	65	0.0	26	
HD	3.20	3.40	0.126	0.134	
HE	3.20	3.40	0.126	0.134	
L	0.07	0.25	0.003	0.010	
L1	0.07	0.25	0.003	0.010	
Lp	0.20	0.40	0.008	0.016	
Lp1	0.25	0.45	0.010	0.018	
Lp2	2.20	2.40	0.087	0.094	
Х	-	0.10	-	0.004	
У	( <b>-</b> (	0.10	-	0.004	

DIM	MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX
b2	101	0.47	u u	0.019
b3	1.5	2.70	-	0.106
I1	-	0.50	-	0.020
12	-	0.55	-	0.022
13	9. <b>5</b> .3	2.40	-	0.094
14	121	3.40	-	0.134

Dimension in mm/inches



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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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